

In re Patent Application of:  
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**Abstract**

An assembly and method for array processing of hermetically sealed Surface Acoustic Wave (SAW) Devices employs a non-conductive material having an array of spaced cavities extending into the material for receiving a SAW die face down, in a flip-chip arrangement. Each cavity has a peripheral recess dimensioned to receive a lid for hermetically sealing the die within the cavity. Conductive paths are provided from the interior of the cavity to the surface of the array for providing an electrical contact with the SAW die. Individual SAW devices are then provided by cutting along separation lines between adjacent cavities after a plurality of die have been hermetically sealed within its cavity.